	Material Composit © Copyright 2005. IPC, I international and Pan-An	Bannockb	urn, Illinois. A	ll rights reserved untions.	under both	This docume level parts, th	ent is a decla he declaratio	aration on enco	of the subsompasses a	stances all lower	within the level mate	manufactur erials for w	er listed i hich the n	tem. N nanufa	ote: if th	e item is an as s engineering	sembly with low responsibility.
					Form Type Distribute						ous Materi	rials and Mfg Information					
Supplier Informat	ion																
Company name*			Company unique ID			Unique ID Authority					Response Date*						
onsemi												2025-07-06					
Contact Name			Title - Contact]	Phone - Contact*					Email - Contact*					
Product-Env-Stewards			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com						
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*							
Product-Env-Stewards			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com						
Requester It	NCP718BSN180T1G 30		n Number Mfr Item Name				Effective Date Version Manufacturing Si		ing Site	Weight*		t*	UOM	Unit Type			
			300 mA Low Iq, Wide Input Voltage LDO - TSOP5 1V8 HZ			2025-07-06	5 THB		12.52			mg	Each				
/Ianufacturing Pr	occess Information	L															
Terminal Pla	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-S		J-STD-020 MSL	ГD-020 MSL Rating		Peak Process Body Temperatu		nperatur	are Max Time at Peak Temp		Temperat	ure l	Number	of Reflow Cyc	les
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		С		30		seconds 3		3		
Comments																	
vel 1 - maximum time	e at peak temperature d	uring sol	dering is 10-3	0 seconds													
or more information	regarding material com	position j	please refer to	page 3													

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Epoxy	0.1	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.003	mg
			Supplier	Silver (Ag)	7440-22-4		0.085	mg
			Supplier	Proprietary	Proprietary Data		0.005	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.007	mg
Lead Frame	6.43	mg	Supplier	Zinc (Zn)	7440-66-6		0.0077	mg
			Supplier	Iron (Fe)	7439-89-6		0.1511	mg
			Supplier	Copper (Cu)	7440-50-8		6.2692	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0019	mg
Mold Compound-Black	5.6	mg		Epoxy resin	proprietary data		0.28	mg
			Supplier	Phenolic Resin	Proprietary Data		0.112	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg
			Supplier	Carbon Black (C)	1333-86-4		0.028	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.04	mg
Plating	0.07	mg	Supplier	Palladium (Pd)	7440-05-3		0.0017	mg
			В	Nickel (Ni)	7440-02-0		0.0616	mg
			Supplier	Gold (Au)	7440-57-5		0.0067	mg
Vire Bond - Cu	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0196	mg